

ABSTRACT OF THE DISCLOSURE

An electronic component holding head, an electronic component mounting apparatus using same, and a method for mounting an electronic component, are provided for use in mounting an electronic component having a positioning mark formed on a film member. The electronic component holding head has a main electronic component holding unit, a vacuum chucking part facing the surface of the electronic component to be held by vacuum chucking so as to hold the electronic component, and a light path for guiding light shined onto a positioning mark formed at an edge part of the electronic component for the purpose of correcting a position offset between the electronic component and the substrate to which the electronic component is to be mounted, the vacuum chucking part holding the electronic component at a position which is on a straight line substantially parallel to an edge of the electronic component and substantially mutually orthogonal over the positioning mark of the electronic component, and which avoids the positioning mark.

15